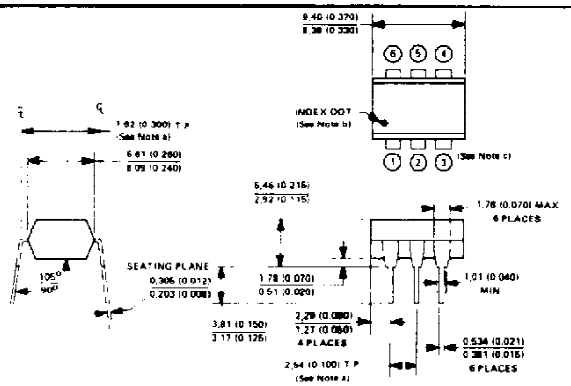
SOOS050 D2491, SEPTEMBER–REVISED DECEMBER 1982

UL LISTED – FILE # E65085

- **GaAs-Diode Infrared Source Optically Coupled to a Silicon N-P-N Phototransistor**
- **Direct-Current Transfer Ratio . . . 10% to 50%**
- **Plug-In Replacements for TIL111 Series**
- **High-Voltage Electrical Isolation . . . 2500 V RMS (3535 V Peak)**

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



NOTES:
a. Leads are within 0,13 mm (0.005 inch) radius of true position (T.P.) with maximum material condition and unit installed.
b. Pin 1 identified by index dot.
Terminal connections:
1. Anode
2. Cathode
3. No internal connection
} Infrared-emitting diode
4. Emitter
5. Collector
6. Base
} Phototransistor

FALLS WITHIN JEDEC MO-001AM DIMENSIONS
ALL LINEAR DIMENSIONS ARE IN MILLIMETERS AND PARENTHETICALLY IN INCHES

absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output RMS Voltage (See Note 1)	2500 V
Collector-Base Voltage	70 V
Collector-Emitter Voltage (See Note 2)	30 V
Emitter-Collector Voltage	7 V
Emitter-Base Voltage	7 V
Input-Diode Reverse Voltage	3 V
Input-Diode Continuous Forward Current at (or below) 25°C Free-Air Temperature (See Note 3)	100 mA
Continuous Phototransistor Power Dissipation at (or below) 25°C Free-Air Temperature (See Note 4)	150 mW
Storage Temperature Range	−55°C to 150°C
Lead Temperature 1,6 mm (1/16 inch) from Case for 10 Seconds	260°C

NOTES: 1. This rating applies for sine-wave operation at 50 or 60 Hz. Service capability is verified by testing in accordance with UL requirements.
2. This value applies when the base-emitter diode is open-circuited.
3. Derate linearly to 100°C free-air temperature at the rate of 1.33 mA/°C.
4. Derate linearly to 100°C free-air temperature at the rate of 2 mW/°C.

electrical characteristics at 25°C free-air temperature

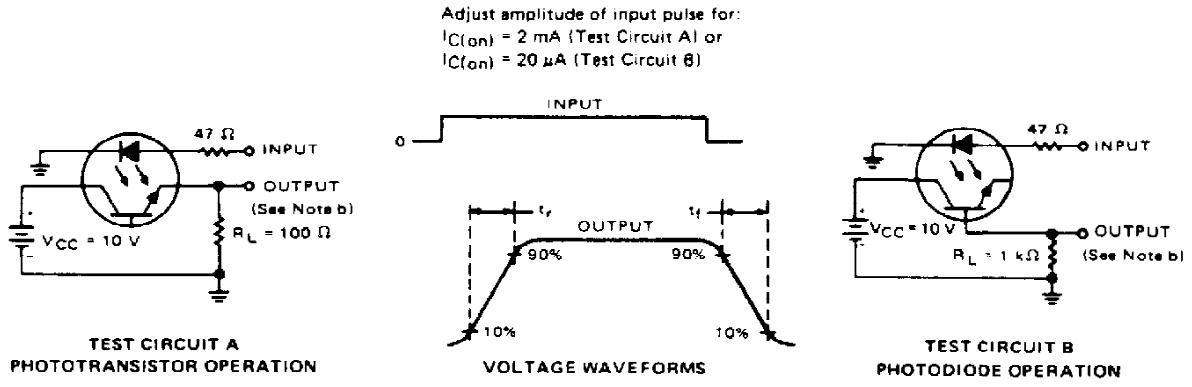
PARAMETER			TEST CONDITIONS	TIL153			TIL154			TIL155			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage		I_C = 10 µA, I_E = 0, I_F = 0	70			70			70			V
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage		I_C = 1 mA, I_B = 0, I_F = 0	30			30			30			V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage		I_E = 10 µA, I_C = 0, I_F = 0	7			7			7			V
I_R	Input Diode Static Reverse Current		V_R = 3 V			10			10			10	µA
$I_{C(on)}$	On-State Collector Current	Phototransistor Operation	V_{CE} = 10 V, I_F = 10 mA, I_B = 0	1	3		2	5		5	9		mA
		Photodiode Operation	V_{CB} = 10 V, I_F = 10 mA, I_E = 0		10			10			10		µA
$I_{C(off)}$	Off-State Collector Current	Phototransistor Operation	V_{CE} = 10 V, I_F = 0, I_B = 0		1	50		1	50		1	50	nA
		Photodiode Operation	V_{CB} = 10 V, I_F = 0, I_E = 0		0.1	20		0.1	20		0.1	20	
h_{FE}	Transistor Static Forward Current Transfer Ratio		V_{CE} = 5 V, I_C = 10 mA, I_F = 0	50	100		100	200		100	550		
V_F	Input Diode Static Forward Voltage		I_F = 10 mA		1.2	1.4		1.2	1.4		1.2	1.4	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage		I_C = 1 mA, I_F = 10 mA, I_B = 0		0.25	0.4		0.25	0.4		0.25	0.4	V
r_{IO}	Input-to-Output Internal Resistance		V_{in-out} = 500 V, See Note 5	10^{11}			10^{11}			10^{11}			Ω
C_{io}	Input-to-Output Capacitance		V_{in-out} = 0, f = 1 MHz, See Note 5		1	1.3		1	1.3		1	1.3	pF

NOTE 5: These parameters are measured between both input diode leads shorted together and all the phototransistor leads shorted together.

switching characteristics at 25°C free-air temperature

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_r Rise Time	Phototransistor	V_{CC} = 10 V, $I_{C(on)}$ = 2 mA, R_L = 100 Ω,			5	10	µs
t_f Fall Time	Operation	See Test Circuit A of Figure 1			5	10	
t_r Rise Time	Photodiode	V_{CC} = 10 V, $I_{C(on)}$ = 20 µA, R_L = 1 kΩ,			1		µs
t_f Fall Time	Operation	See Test Circuit B of Figure 1			1		

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT A
PHOTOTRANSISTOR OPERATION

VOLTAGE WAVEFORMS

TEST CIRCUIT B
PHOTODIODE OPERATION

NOTES: a. The input waveform is supplied by a generator with the following characteristics: Z_{out} = 50 Ω, t_r ≤ 15 ns, duty cycle ≈ 1%, t_w = 100 μs.
b. The output waveform is monitored on an oscilloscope with the following characteristics: t_r ≤ 12 ns, R_{in} ≥ 1 MΩ, C_{in} ≤ 20 pF.

FIGURE 1—SWITCHING TIMES

TYPICAL CHARACTERISTICS

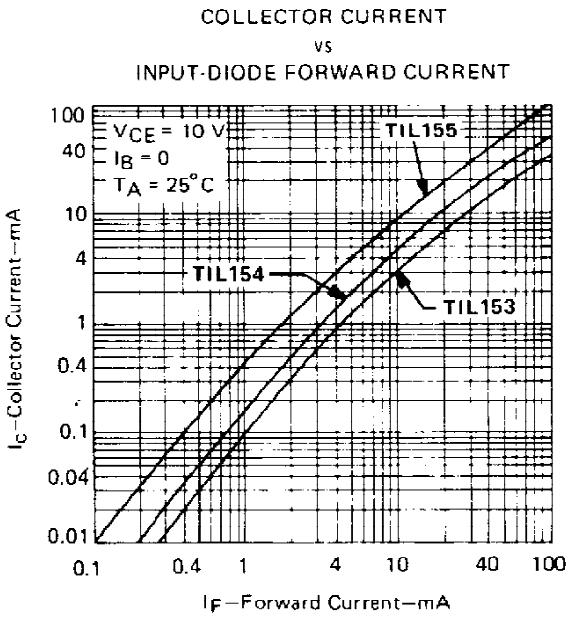


FIGURE 2

TYPICAL CHARACTERISTICS

TIL153

COLLECTOR CURRENT
vs
COLLECTOR-EMITTER VOLTAGE

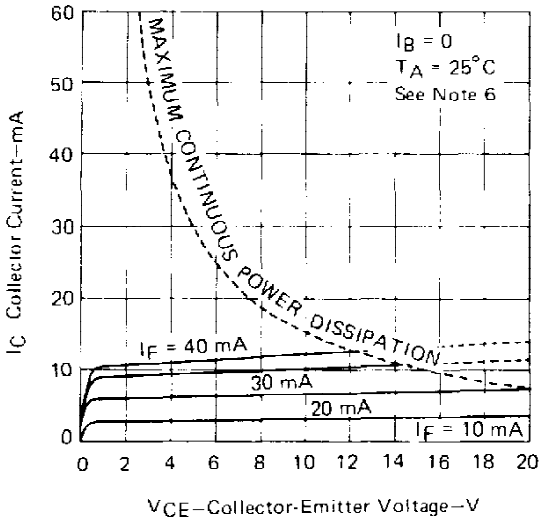


FIGURE 3

TIL154

COLLECTOR CURRENT
vs
COLLECTOR-EMITTER VOLTAGE

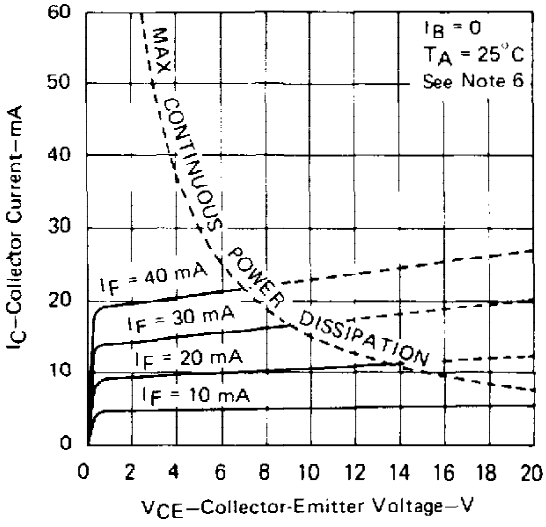


FIGURE 4

TIL155

COLLECTOR CURRENT
vs
COLLECTOR-EMITTER VOLTAGE

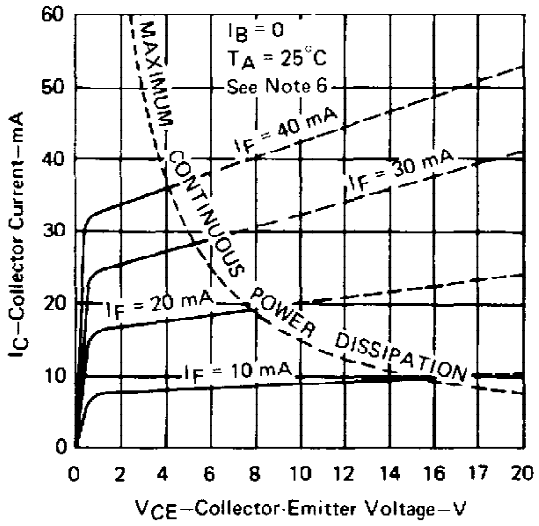


FIGURE 5

RELATIVE ON-STATE COLLECTOR CURRENT
vs
FREE-AIR TEMPERATURE

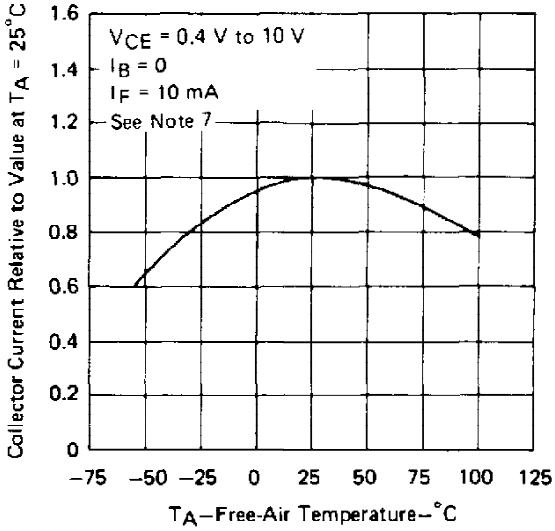


FIGURE 6

NOTES: 6. Pulse operation of input diode is required for operation beyond limits shown by dotted lines.
7. These parameters were measured using pulse techniques. t_w = 1 ms, duty cycle ≤ 2%.

TYPICAL CHARACTERISTICS

OFF-STATE COLLECTOR CURRENT
vs
FREE-AIR TEMPERATURE

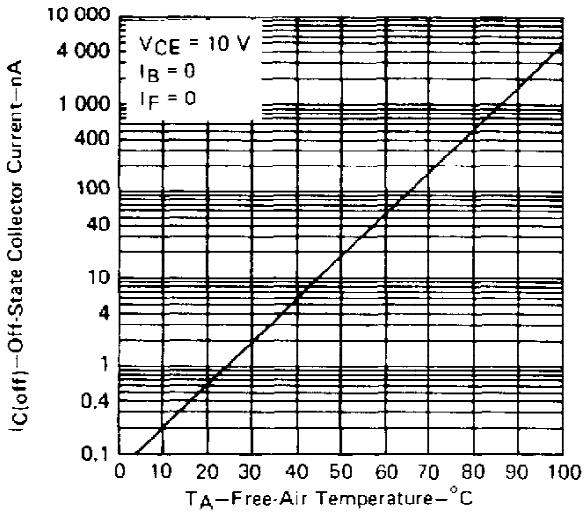


FIGURE 7

NORMALIZED TRANSISTOR STATIC FORWARD
CURRENT TRANSFER RATIO
vs
ON-STATE COLLECTOR CURRENT

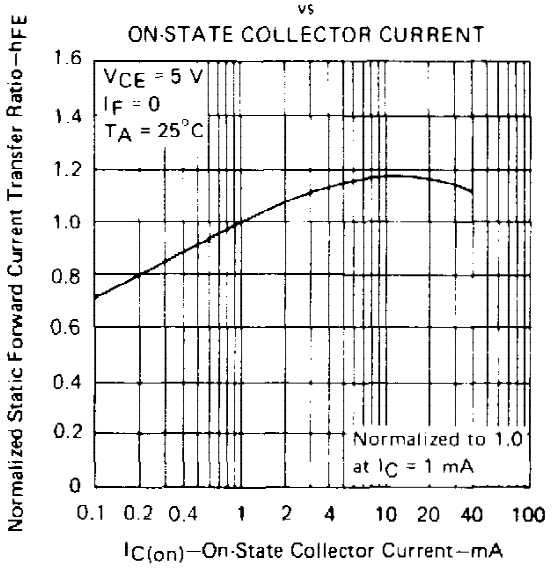


FIGURE 8

INPUT DIODE FORWARD
CONDUCTION CHARACTERISTICS

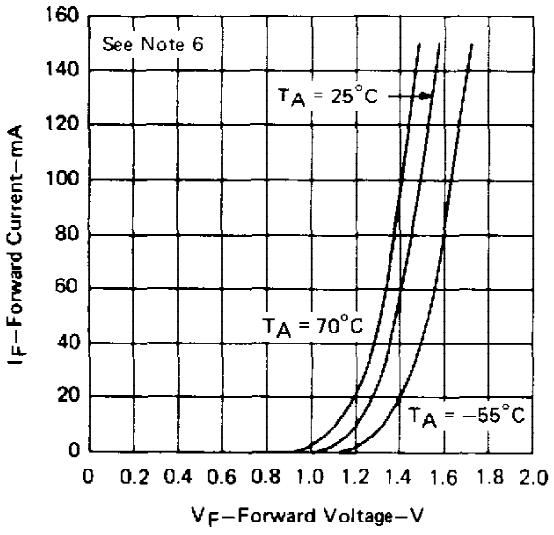


FIGURE 9

COLLECTOR CURRENT
vs
MODULATION FREQUENCY

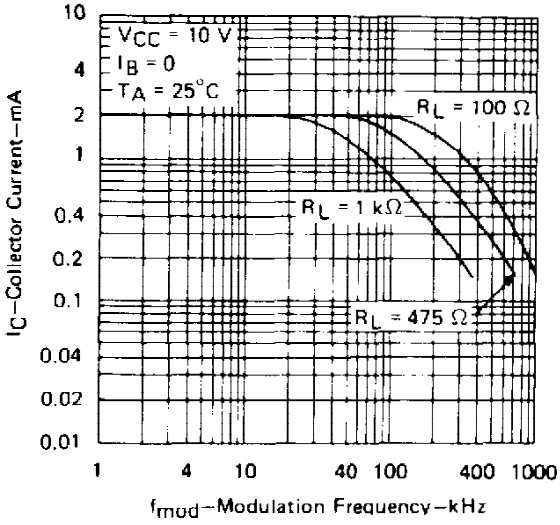


FIGURE 10

NOTE 6: These parameters were measured using pulse techniques, t_w = 1 ms, duty cycle ≤ 2%

IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.